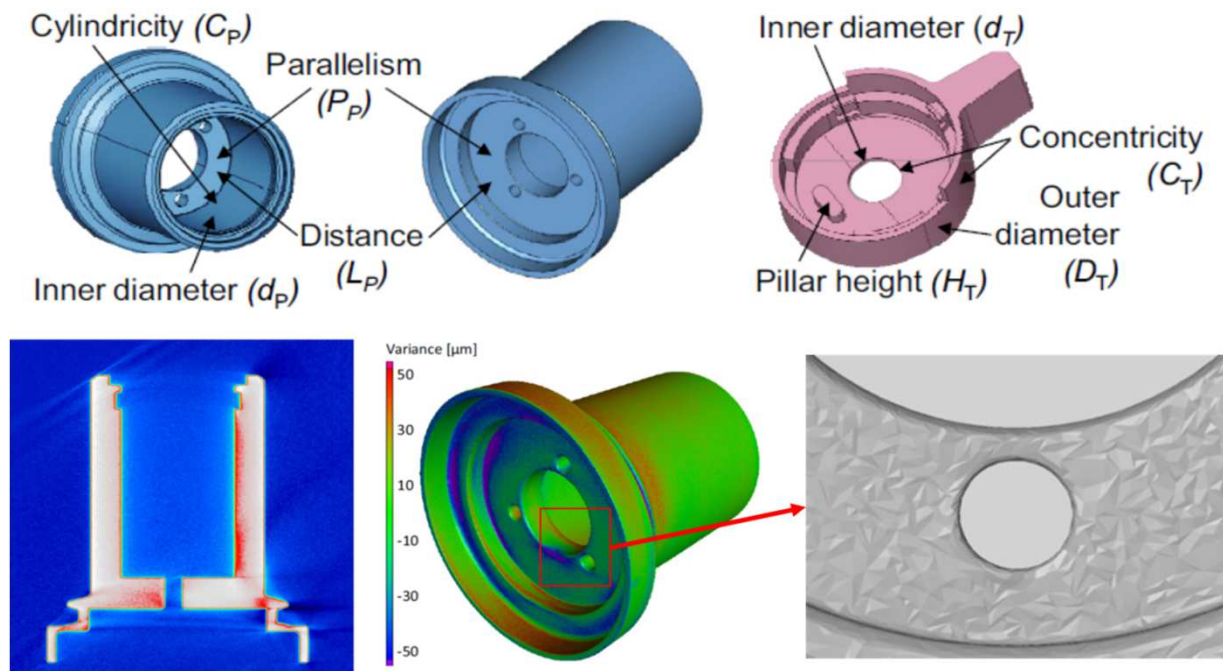


Micro CT (Micro Computed Tomography)

- 斷層掃描技術具有穿透待測物本體內部的能力，本團隊已具備微型電腦斷層掃描的技術經驗，可提供半導體及航太等高科技產業X光層析掃描物質缺陷檢測服務或可攜式檢測系統設計。
- 檢測部份多是平面、曲面或有限的環形幾何物體，範圍通常位於受檢測物體表面下約3至5公分。
- 應用於如半導體及航太科技等高科技產業技術領域。
- Computed tomography technology has the ability to look through an object. Our team has the capability and experience in this field and can provide our customers related inspection service, especially in the semiconductor, aerospace and high tech industry. We can also supply customized system design and R&D service.
- Objects for inspection can be either flat, curved, or partial circular shape. Usual inspection depth can be 3-5cm below the surface of the object.

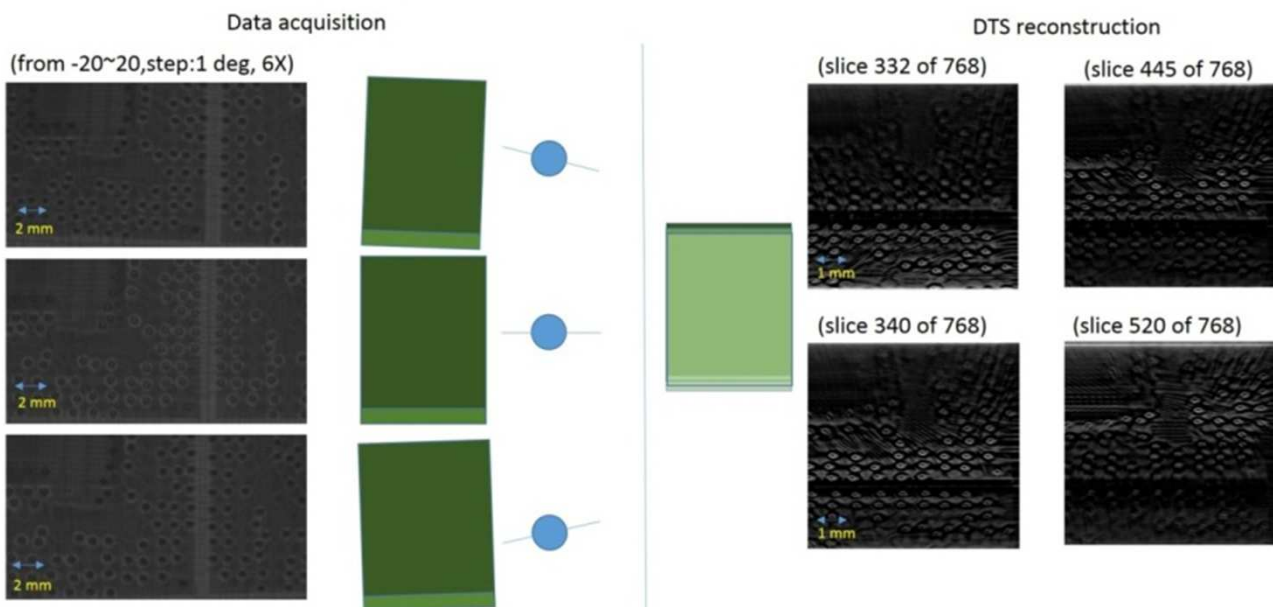


X光斷層掃描發展歷程

- 使用X光斷層掃描進行非破壞性檢測可回溯至1970年
- 首次在醫學上的應用
- 自此使用X光斷層掃描進行三維分析的新科學提出
- X光電腦斷層的應用由醫學開始跨躍至考古學、光電物理學乃至工業品管應用、材料科學等，被應用於工業檢測已不亞於醫學上的應用了
- 一般工業檢測：二維X光機線性掃描=>三維斷層掃描檢測抽檢 => 隨著重建技術的成熟，我們只要針對待測物進行樣本掃描，就能快速得到待測物的三維資訊，因此可被運用到線上全檢。

X-Ray Computed Tomography Development History

- Usage of X-Ray Computed Tomography for non-destructive-testing (NDT) can be traced back to 1970. The first time is used for medical purpose.
- Since then 3D computed tomography was suggested.
- This technology was spread out from medical application to anthropology, opto-electronics, physics, material sciences, and industrial applications.

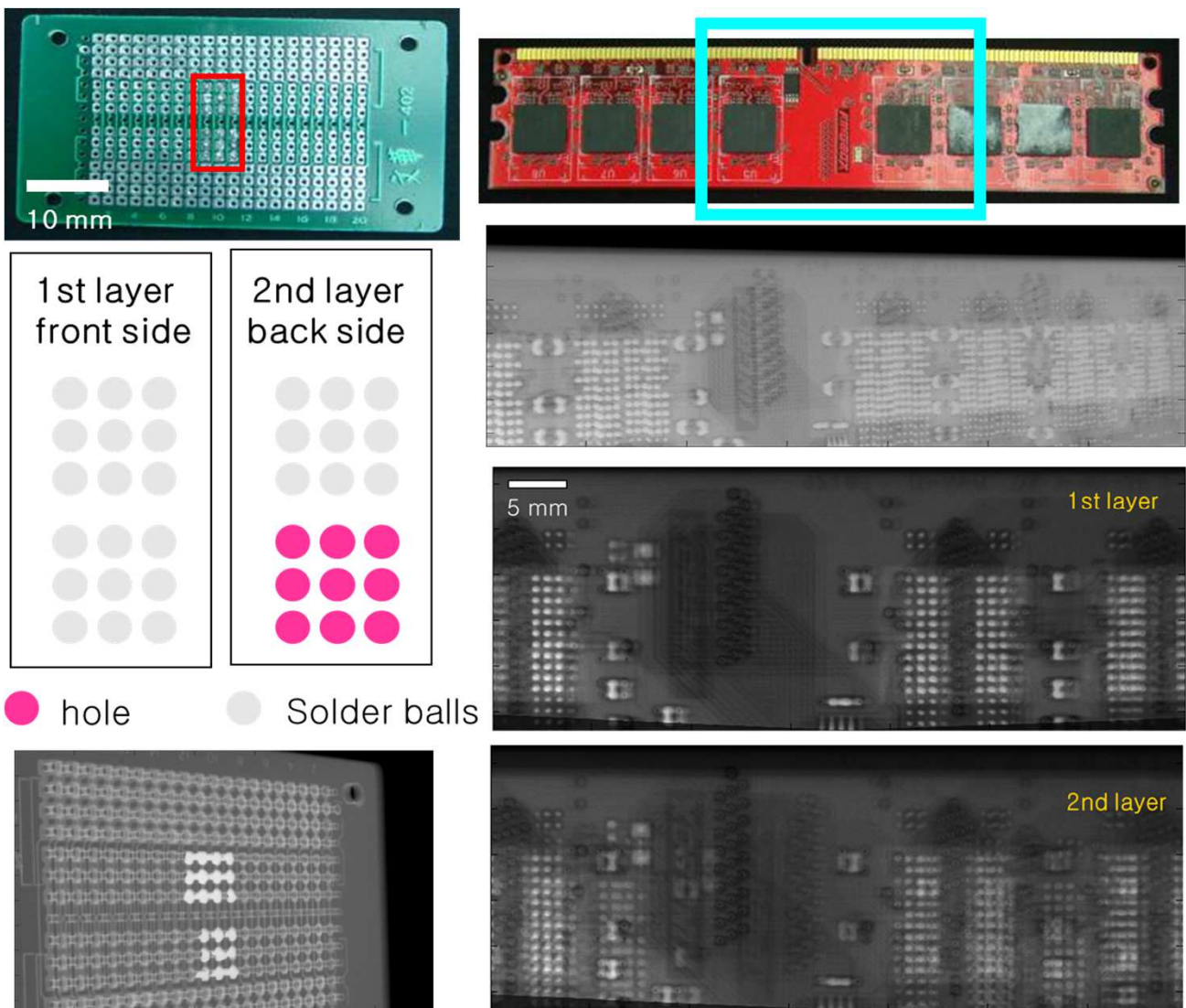


BGA焊球檢測

- 可3D檢視PCB及DRAM模組各層剖面的缺陷

BGA Solder Ball Inspection

- We can 3D inspect the defects in all layers of PCB and DRAM modules.



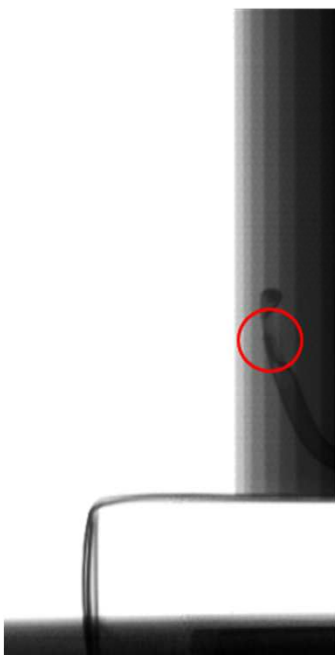
應用：

- 矽晶太陽能板裂隙檢測
- 鋁製鑄件缺損檢測

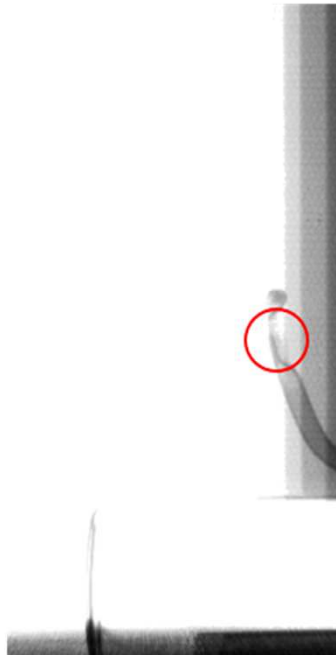
Other Application：

- Crystalline silicon solar cell crack inspection
- Extruded/forged/cast aluminum part defect inspection

60kV, 7mA



70kV, 7mA



75kV, 7mA

